1/5

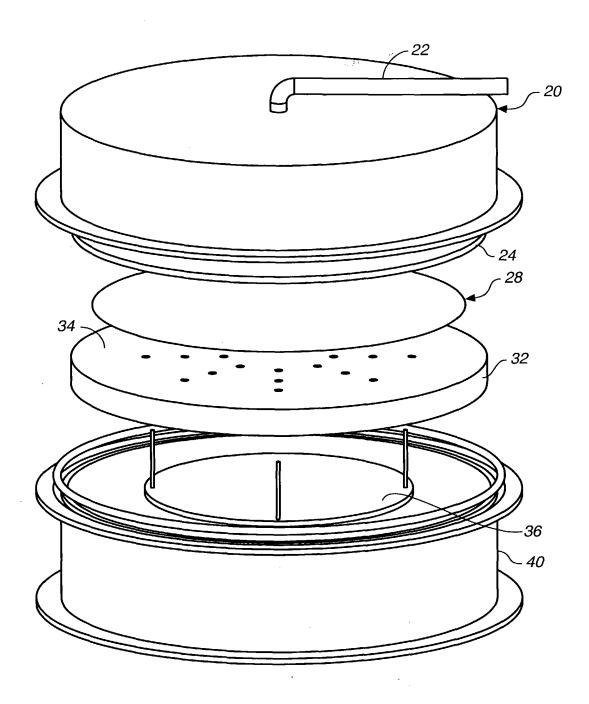


FIG.\_1 (PRIOR ART)

Appln. No.: Unassigned Docket No.: SENS.007US1
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Inventors: Wayne Glenn Renken Exp. Mail: EU962645425US
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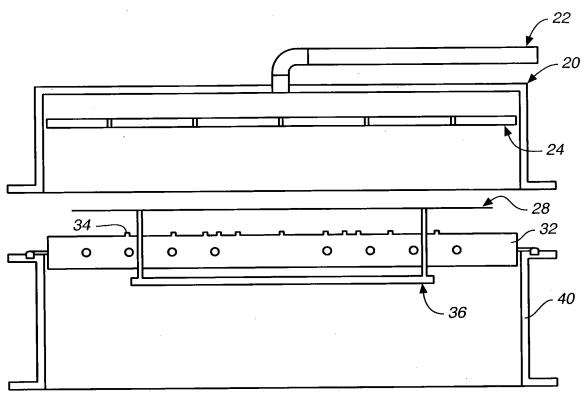


FIG.\_2 (PRIOR ART)

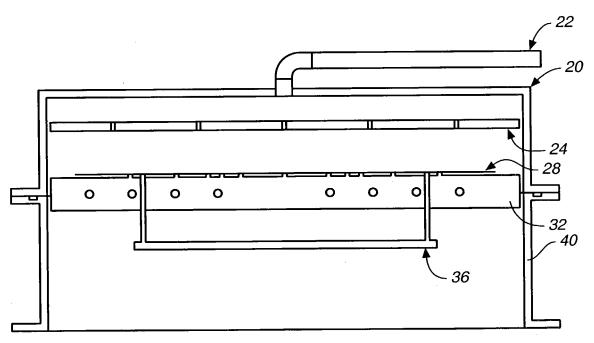
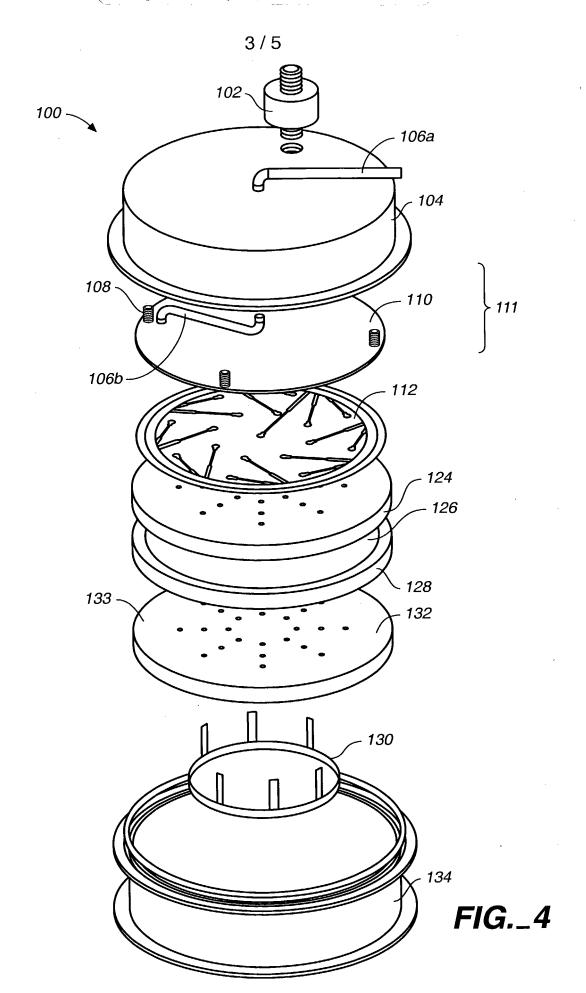
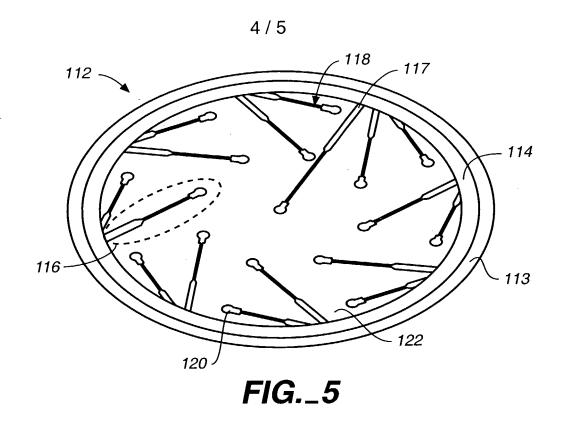


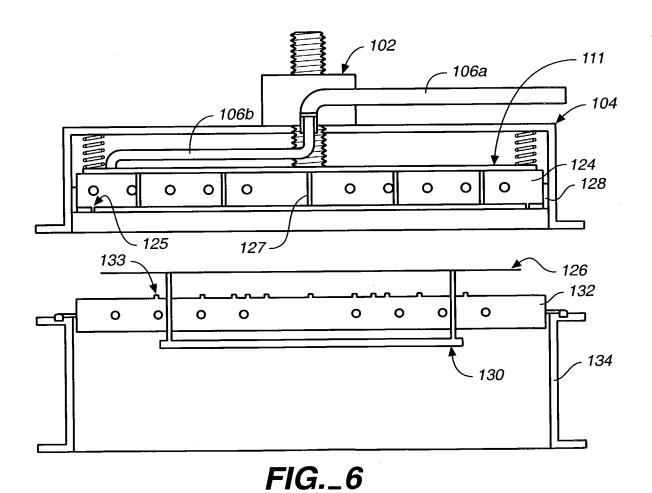
FIG.\_3 (PRIOR ART)

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Inventors: Wayne Glenn Renken Exp. Mail: EU962645425US
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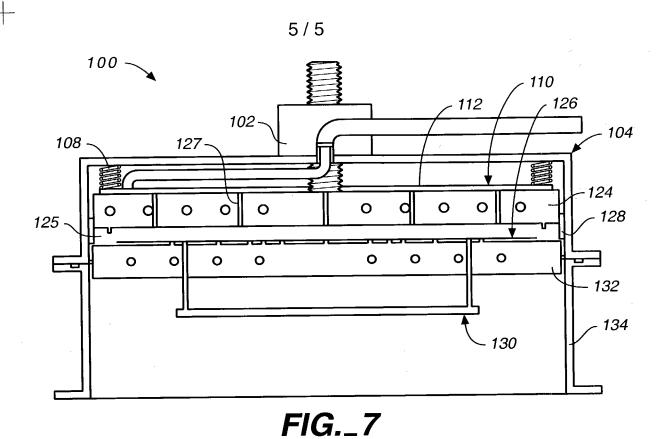
Appln. No.: Unassigned Docket No.: SENS.007US1
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Inventors: Wayne Glenn Renken Exp. Mail: EU962645425US
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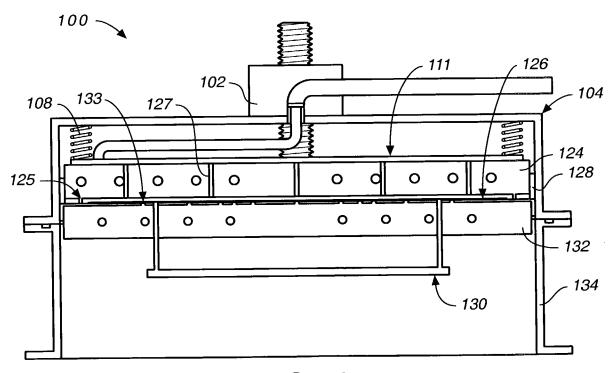


FIG.\_8